



**SEME
LAB**

IRF150

ELECTRICAL CHARACTERISTICS ($T_{case} = 25^\circ C$ unless otherwise stated)

| Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|---|---|------|-------|------------|----------------|
| STATIC ELECTRICAL RATINGS | | | | | |
| BV_{DSS} | Drain – Source Breakdown Voltage $V_{GS} = 0$ $I_D = 1mA$ | 100 | | | V |
| ΔBV_{DSS} | Temperature Coefficient of Breakdown Voltage $I_D = 1mA$ | | 0.13 | | $V/^\circ C$ |
| $R_{DS(on)}$ | Static Drain – Source On-State Resistance 1 $V_{GS} = 10V$ $I_D = 24A$ | | 0.055 | | Ω |
| | $V_{GS} = 10V$ $I_D = 38A$ | | 0.065 | | |
| $V_{GS(th)}$ | Gate Threshold Voltage $V_{DS} = V_{GS}$ $I_D = 250mA$ | 2 | | 4 | V |
| g_{fs} | Forward Transconductance ¹ $V_{DS} \geq 15V$ $I_{DS} = 24A$ | 9 | | | S (Ω) |
| I_{DSS} | Zero Gate Voltage Drain Current $V_{GS} = 0$ $V_{DS} = 0.8BV_{DSS}$ | | 25 | | μA |
| | $T_J = 125^\circ C$ | | 250 | | |
| I_{GSS} | Forward Gate – Source Leakage $V_{GS} = 20V$ | | | 100 | nA |
| I_{GSS} | Reverse Gate – Source Leakage $V_{GS} = -20V$ | | | -100 | |
| DYNAMIC CHARACTERISTICS | | | | | |
| C_{iss} | Input Capacitance $V_{GS} = 0$ | | 3700 | | pF |
| C_{oss} | Output Capacitance $V_{DS} = 25V$ | | 1100 | | |
| C_{rss} | Reverse Transfer Capacitance $f = 1MHz$ | | 200 | | |
| Q_g | Total Gate Charge $V_{GS} = 10V$ | 50 | | 125 | nC |
| Q_{gs} | Gate – Source Charge $I_D = 38A$ | 8 | | 22 | |
| Q_{gd} | Gate – Drain ("Miller") Charge $V_{DS} = 0.5BV_{DSS}$ | 25 | | 65 | |
| $t_{d(on)}$ | Turn-On Delay Time $V_{DD} = 50V$ | | | 35 | ns |
| t_r | Rise Time $I_D = 38A$ | | | 190 | |
| $t_{d(off)}$ | Turn-Off Delay Time $R_G = 2.35\Omega$ | | | 170 | |
| t_f | Fall Time | | | 130 | |
| SOURCE – DRAIN DIODE CHARACTERISTICS | | | | | |
| I_S | Continuous Source Current | | | 38 | A |
| I_{SM} | Pulse Source Current ² | | | 152 | |
| V_{SD} | Diode Forward Voltage ¹ $I_S = 38A$ $T_J = 25^\circ C$ $V_{GS} = 0$ | | | 1.8 | V |
| t_{rr} | Reverse Recovery Time $I_F = 38A$ $T_J = 25^\circ C$ | | | 500 | ns |
| Q_{rr} | Reverse Recovery Charge ¹ $d_i / d_t \leq 100A/\mu s$ $V_{DD} \leq 50V$ | | | 2.9 | μC |
| t_{on} | Forward Turn-On Time | | | Negligible | |
| PACKAGE CHARACTERISTICS | | | | | |
| L_D | Internal Drain Inductance (measured from 6mm down drain lead to centre of die) | | 5.0 | | nH |
| L_S | Internal Source Inductance (from 6mm down source lead to source bond pad) | | 13 | | |
| THERMAL CHARACTERISTICS | | | | | |
| $R_{\theta JC}$ | Thermal Resistance Junction – Case | | | 0.83 | $^\circ C/W$ |
| $R_{\theta CS}$ | Thermal Resistance Case – Sink | | 0.12 | | |
| $R_{\theta JA}$ | Thermal Resistance Junction – Ambient | | | 30 | |

Notes

- 1) Pulse Test: Pulse Width $\leq 300ms$, $\delta \leq 2\%$
- 2) Repetitive Rating – Pulse width limited by maximum junction temperature.